



Shenzhen Flourish Electronics Co., LTD

(C) D- C

FILE NO.

QC-T4-09

Ver:

1.0

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SPECIFICATION FOR APPROVAL





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Features



Test Condition



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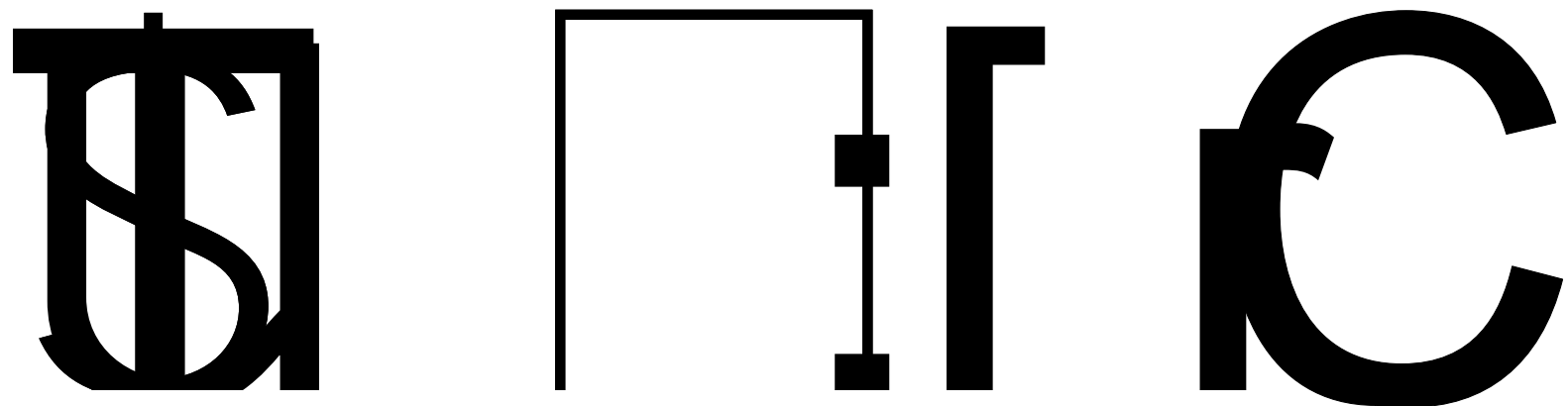
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(Specification details & dimensions)

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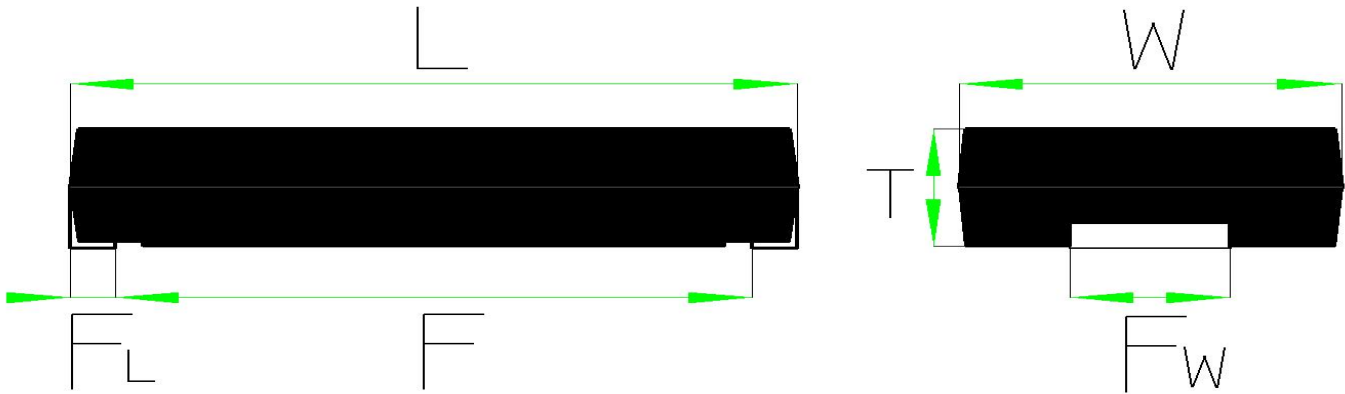
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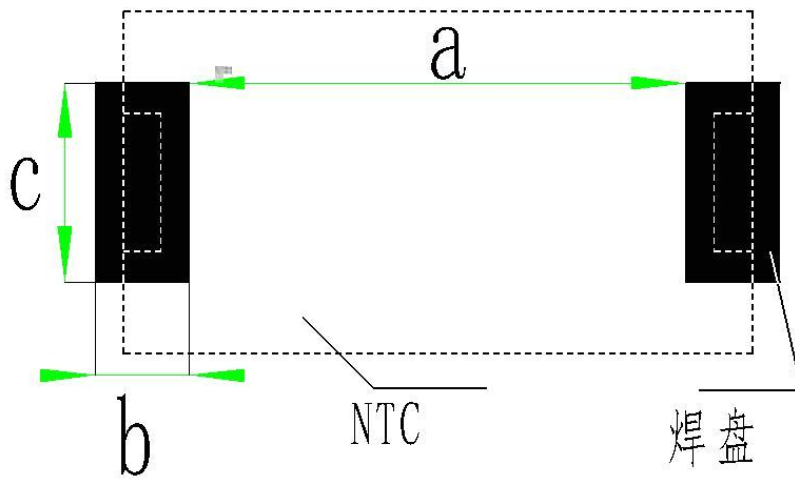
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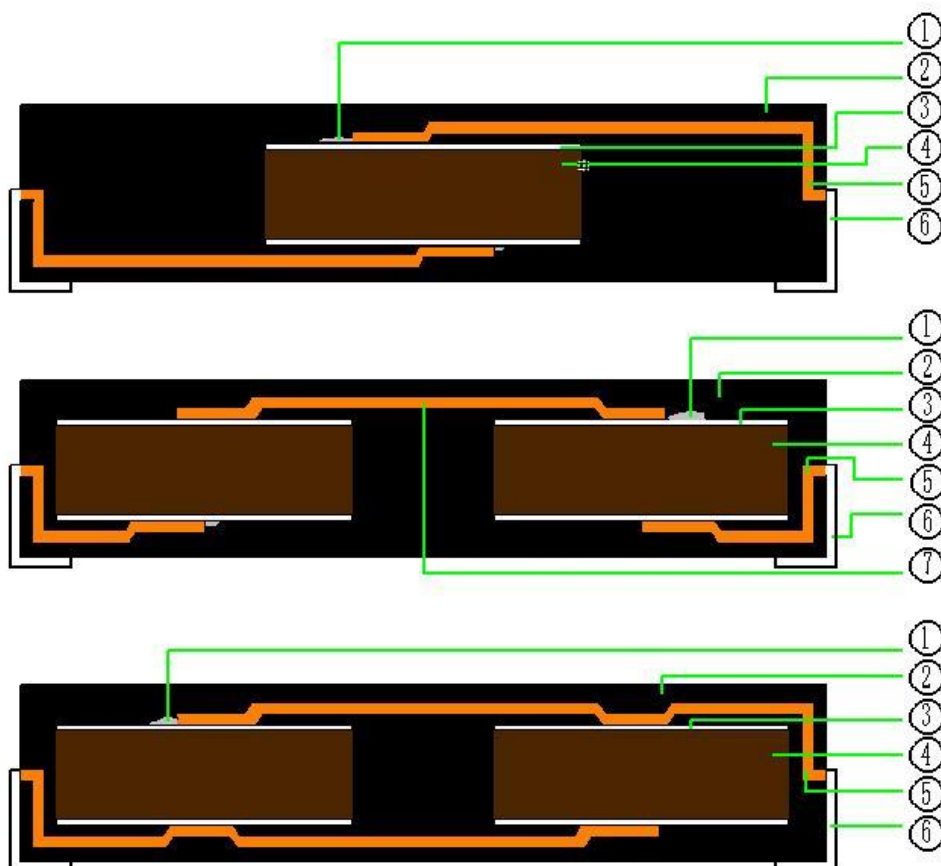
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(Marking Explain)

Safety Certification:

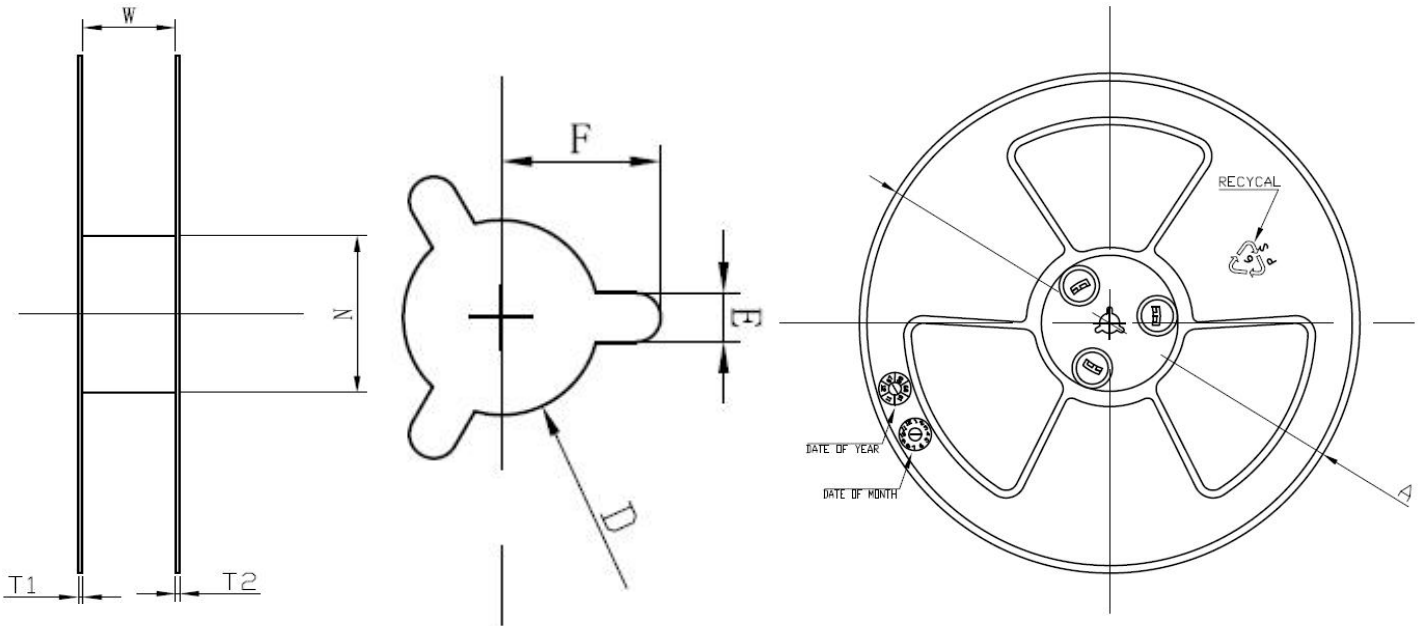
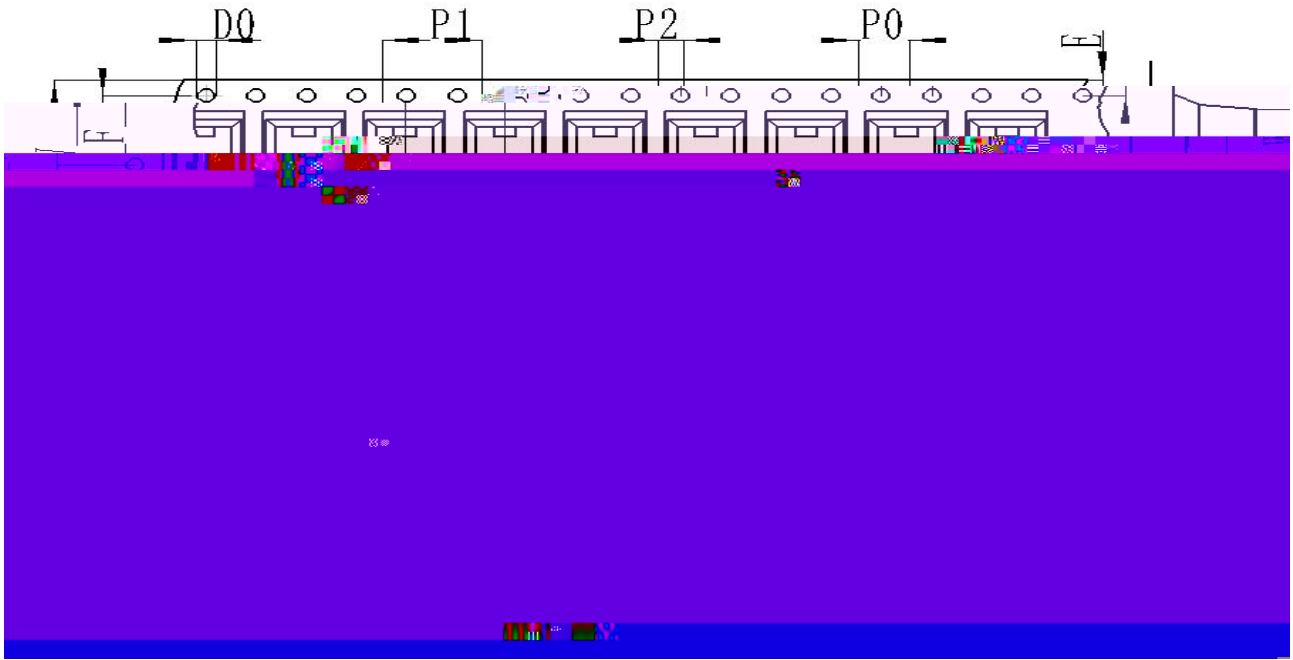


Structure

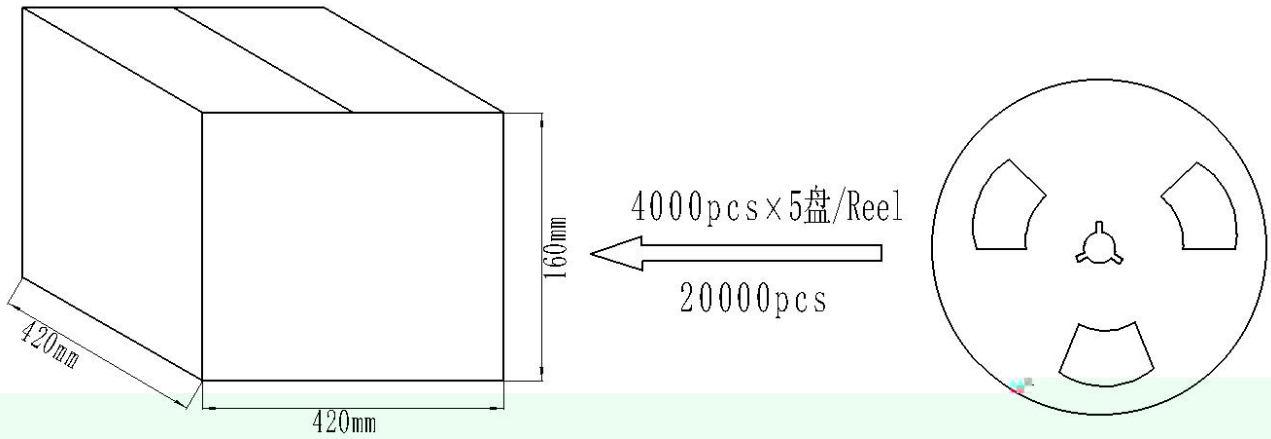


packing description

6.1



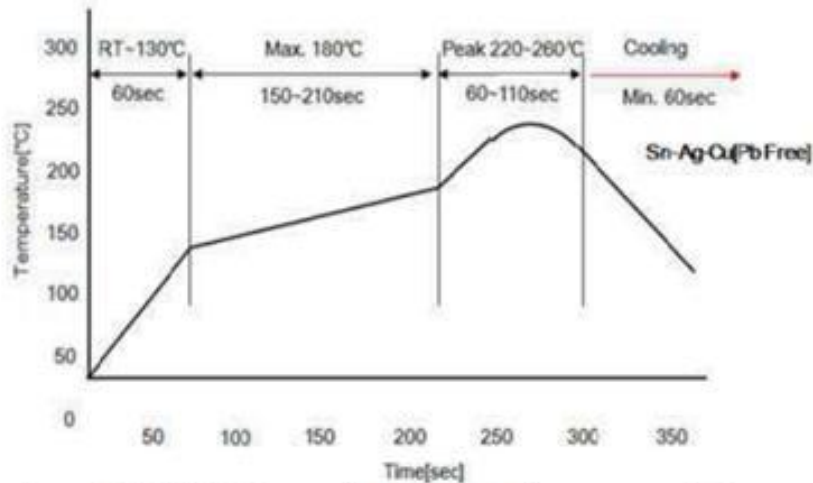
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Welding according to the instruction

7.1

☆ 回流焊接曲线



| 温区 | 温度范围 (°C) | 时间 (sec) | 备注 |
|----|------------------|----------|--------------------------------|
| a | RT~130 | 60 | 焊锡: Sn-Ag-Cu 高温时间: < 10 sec |
| b | 180 max | 150~210 | |
| c | 220~260(260 max) | 60~110 | |
| d | 220~RT | 60 min | |

当焊接温度低于锡的熔点时，贴片镀锡端子的可焊性将下降。使用之前请确认贴片镀锡电极的可焊性
焊接区出风口及内部空间最高温度不能超过 280°C，温度超过时，会造成产品发生失效。由于超温使用所造成的不良，我司不予承担责任。



7.2.

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|-------|---------------------|-------------------------------------|
| Level | Bake@40C 5%RH | |
| | Saturated@30C/85%RH | At limit of Floor life+70% 30C 80RH |
| | 70days | 60days |

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7.4

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